

Letter from the Editors

Welcome to the January 2001 issue of EEE Links.

The EEE Links Newsletter is a great way to share practical experiences and discoveries with your colleagues.

The NASA Electronic Parts and Packaging (NEPP) Program says goodbye to Mr. Tom Gindorf and best of luck in his retirement. We welcome Mr. Chuck Barnes, JPL, as the new NEPP Program Manager. Mr. Choon Lee, JPL, has been named the Electronic Parts (EPAR) Program Manager.

In our interview with Brian Keegan, NASA's Chief Engineer, he stressed the importance of the NEPP Program in performing technical assessments, characterizations, and evaluations of newly available and advanced (emerging) electronic parts and packaging, to enable their rapid infusion into NASA's hardware projects, thereby reducing the cost of mission success.

By doing this, the NEPP Program enables NASA's projects and missions to be "faster, better, cheaper". Please keep us informed with your questions and needs so we can continue to improve the upcoming issues to meet your needs.

You may also submit articles for upcoming issues anytime. Check out the focus for future EEE Links at http://nepp.nasa.gov/imd/eee_links.

To learn more about the NEPP Program visit our web site, <http://nepp.nasa.gov>.

The EEE Links Newsletter is published under the NASA Electronic Parts and Packaging (NEPP) Program. This is the first issue published by QSS Group, Inc., the new EEE Links Editor.

Thank you,

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QSS Group, Inc.